PATENT ASSIGNMENT

Electronic Version v1.1
Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Akishige Nakajima	09/21/2007
Yasushi Shigeno	09/21/2007
Tomoyuki Ishikawa	09/21/2007

RECEIVING PARTY DATA

Name:	RENESAS TECHNOLOGY CORP.
Street Address:	6-2, Otemachi 2-chome
Internal Address:	Chiyoda-ku
City:	Tokyo
State/Country:	JAPAN

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	11960242

CORRESPONDENCE DATA

Fax Number: (703)684-1157
Correspondence will be sent via US Mail when the fax attempt is unsuccessful.
Phone: 7036841120
Email: lmaxwell@mmiplaw.com
Correspondent Name: MATTINGLY & MALUR, P.C.
Address Line 1: 1800 Diagonal Road
Address Line 2: Suite 370
Address Line 4: Alexandria, VIRGINIA 22314

ATTORNEY DOCKET NUMBER:	REN-6096
NAME OF SUBMITTER:	John R. Mattingly

Total Attachments: 1
source=11960242Assignment#page1.tif

CH $40.00 11960242

ASSIGNMENT
（譲 渡 証）

As a below named Inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar ($1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by Renesas Technology Corp.,
a corporation organized under the laws of Japan,
located at 6-2, Otemachi 2-chome, Chiyoda-ku, Tokyo, Japan,
receipt of which is hereby acknowledged I do hereby sell and assign to said Renesas Technology Corp.,
its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

SEMICONDUCTOR INTEGRATED CIRCUIT DEVICE AND HIGH-FREQUENCY POWER AMPLIFIER MODULE

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted,
to be held and enjoyed by said Renesas Technology Corp.,
its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said Renesas Technology Corp.

Signed on the date(s) indicated aside our signatures:

	INVENTOR(S) (発明者フルネームサイン)	Date Signed (署名日)
1)	Akishige Nakajima Akishige NAKAJIMA	21 /September/2007
2)	Yasushi Shigeno Yasushi SHIGENO	21 / September / 2007
3)	Tomoyuki Ishikawa Tomoyuki ISHIKAWA	21/ September/2007
4)		
5)		
6)		
7)		
8)		
9)		
10)		